

## N-channel 600 V, 0.168 $\Omega$ typ., 18 A MDmesh™ M2 Power MOSFET in a TO-220FP ultra narrow leads package

Datasheet - production data

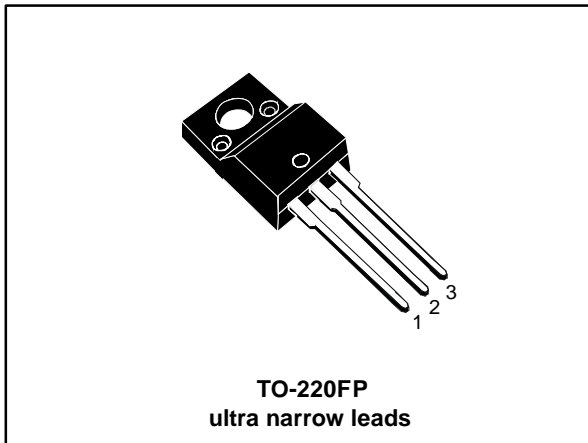
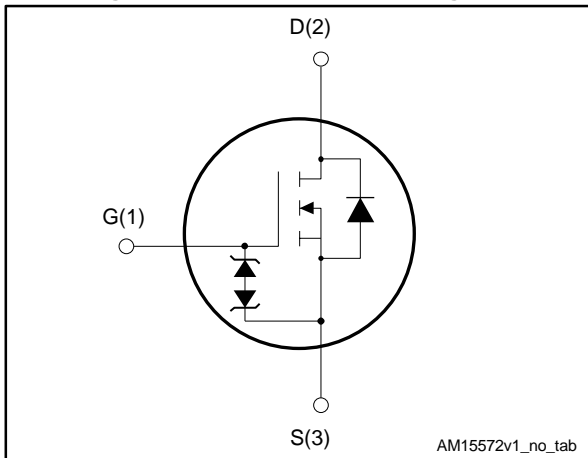


Figure 1: Internal schematic diagram



### Features

Order code	V <sub>DS</sub>	R <sub>DS(on)</sub> max	I <sub>D</sub>
STFU24N60M2	600 V	0.19 $\Omega$	18 A

- Extremely low gate charge
- Lower R<sub>DS(on)</sub> x area vs previous generation
- Low gate input resistance
- 100% avalanche tested
- Zener-protected

### Applications

- Switching applications
- LLC converters, resonant converters

### Description

This device is an N-channel Power MOSFET developed using MDmesh™ M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

Table 1: Device summary

Order code	Marking	Package	Packing
STFU24N60M2	24N60M2	TO-220FP ultra narrow leads	Tube

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# 1 Electrical ratings

**Table 2: Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{GS}$	Gate-source voltage	$\pm 25$	V
$I_D$	Drain current (continuous) at $T_C = 25\text{ °C}$	18 <sup>(1)</sup>	A
$I_D$	Drain current (continuous) at $T_C = 100\text{ °C}$	12 <sup>(1)</sup>	A
$I_{DM}$ <sup>(2)</sup>	Drain current (pulsed)	72 <sup>(1)</sup>	A
$P_{TOT}$	Total dissipation at $T_C = 25\text{ °C}$	30	W
$V_{ISO}$	Insulation withstand voltage (RMS) from all three leads to external heat sink ( $t = 1\text{ s}$ ; $T_C = 25\text{ °C}$ )	2500	V
$dv/dt$ <sup>(3)</sup>	Peak diode recovery voltage slope	15	V/ns
$dv/dt$ <sup>(4)</sup>	MOSFET $dv/dt$ ruggedness	50	
$T_{stg}$	Storage temperature	- 55 to 150	°C
$T_j$	Max. operating junction temperature		

**Notes:**

<sup>(1)</sup>Limited by maximum junction temperature.

<sup>(2)</sup>Pulse width limited by safe operating area.

<sup>(3)</sup> $I_{SD} \leq 18\text{ A}$ ,  $di/dt \leq 400\text{ A}/\mu\text{s}$ ;  $V_{DSpeak} < V_{(BR)DSS}$ ,  $V_{DD} = 400\text{ V}$ .

<sup>(4)</sup> $V_{DS} \leq 480\text{ V}$ .

**Table 3: Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	4.2	°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient max	62.5	

**Table 4: Avalanche characteristics**

Symbol	Parameter	Value	Unit
$I_{AR}$	Avalanche current, repetitive or not repetitive (pulse width limited by $T_{jmax}$ )	3.5	A
$E_{AS}$	Single pulse avalanche energy (starting $T_j = 25\text{ °C}$ , $I_D = I_{AR}$ ; $V_{DD} = 50\text{ V}$ )	180	mJ

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 5: On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$ , $V_{GS} = 0\text{ V}$	600			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = 600\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 600\text{ V}$ , $T_C = 125\text{ °C}$			100	$\mu\text{A}$
$I_{GSS}$	Gate-body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 25\text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	2	3	4	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$ , $I_D = 9\text{ A}$		0.168	0.19	$\Omega$

**Table 6: Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	-	1060	-	pF
$C_{oss}$	Output capacitance		-	55	-	pF
$C_{rss}$	Reverse transfer capacitance		-	2.2	-	pF
$C_{oss\text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{DS} = 0\text{ to }480\text{ V}$ , $V_{GS} = 0\text{ V}$	-	258	-	pF
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz}$ , $I_D = 0$	-	7	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 480\text{ V}$ , $I_D = 18\text{ A}$ , $V_{GS} = 10\text{ V}$ ( see <a href="#">Figure 15: "Test circuit for gate charge behavior"</a> )	-	29	-	nC
$Q_{gs}$	Gate-source charge		-	6	-	nC
$Q_{gd}$	Gate-drain charge		-	12	-	nC

**Notes:**

<sup>(1)</sup> $C_{oss\text{ eq.}}$  is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$ .

**Table 7: Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 300\text{ V}$ , $I_D = 9\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$ ( see <a href="#">Figure 14: "Test circuit for resistive load switching times"</a> and <a href="#">Figure 19: "Switching time waveform"</a> )	-	14	-	ns
$t_r$	Rise time		-	9	-	ns
$t_{d(off)}$	Turn-off delay time		-	60	-	ns
$t_f$	Fall time		-	15	-	ns

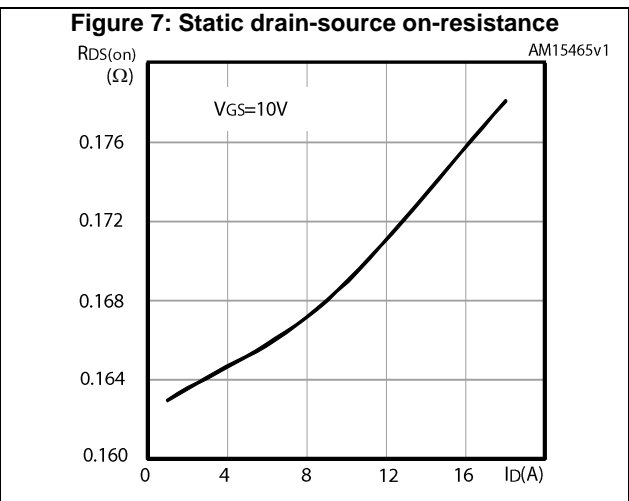
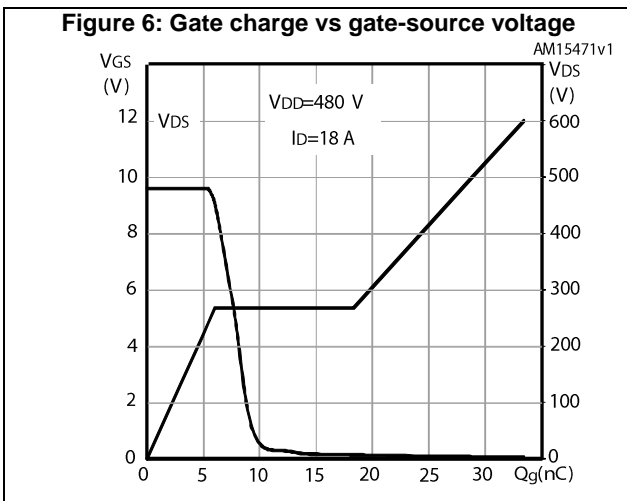
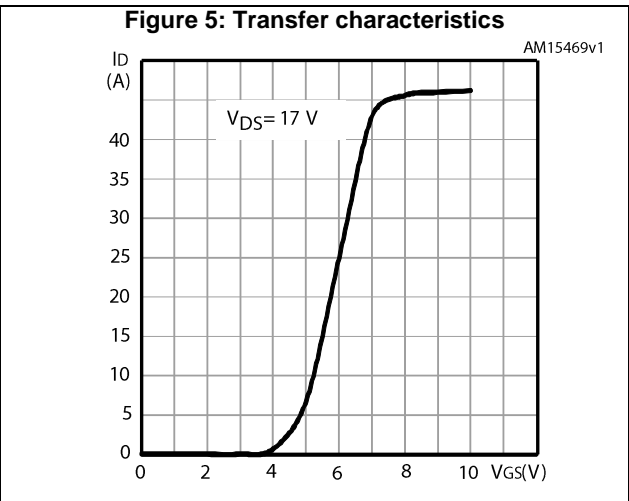
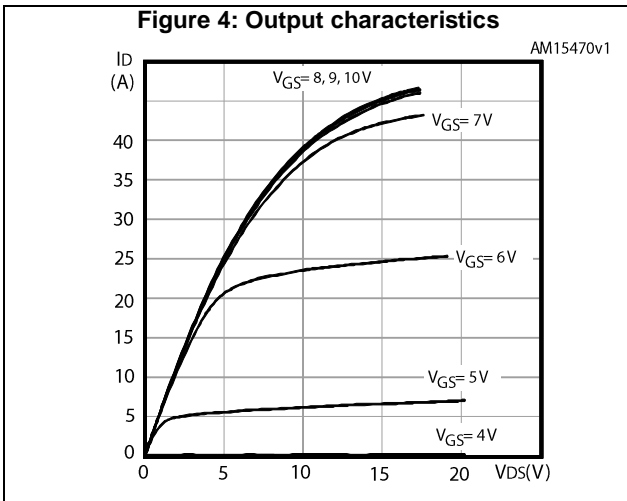
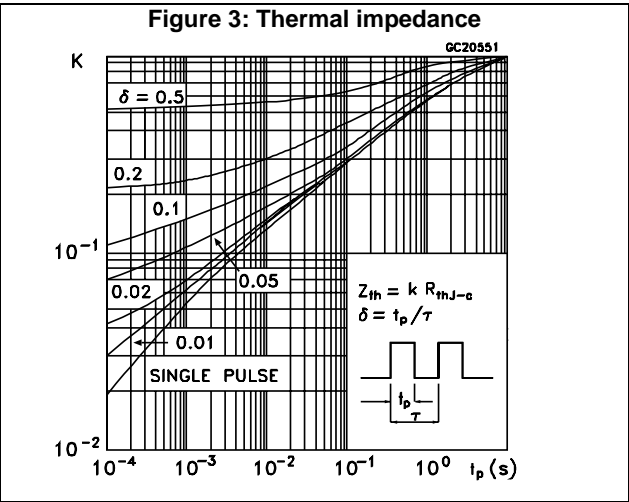
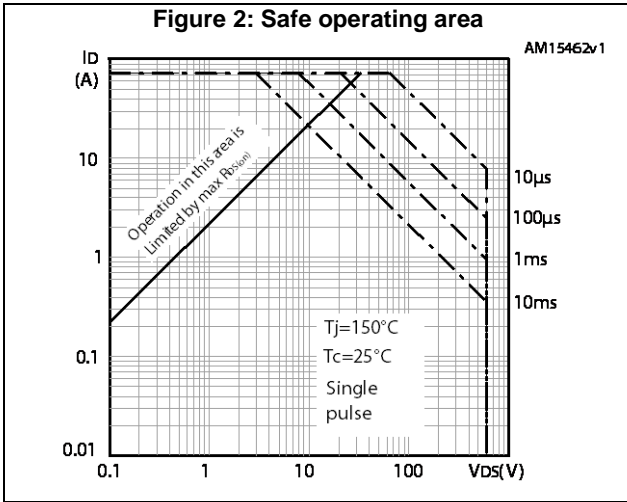
Table 8: Source drain diode

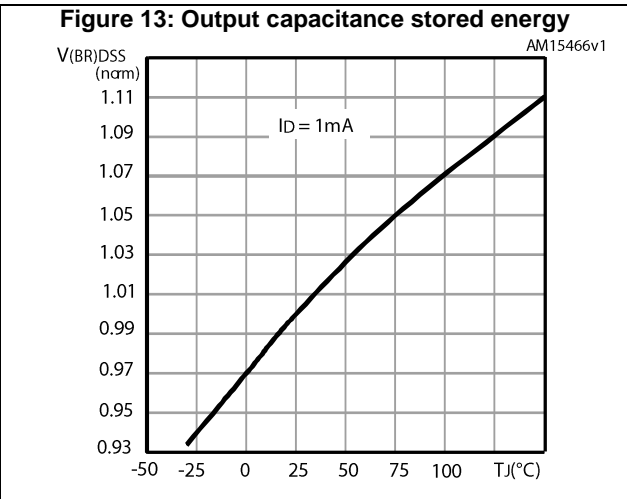
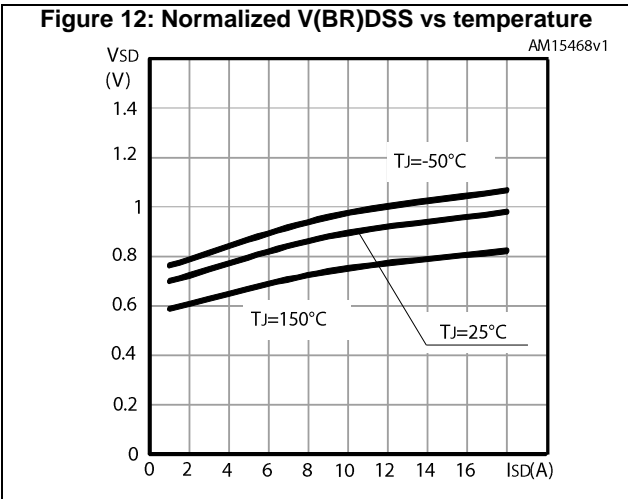
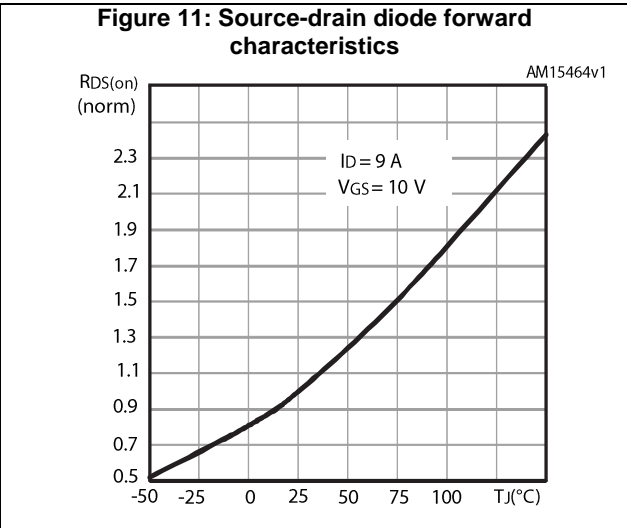
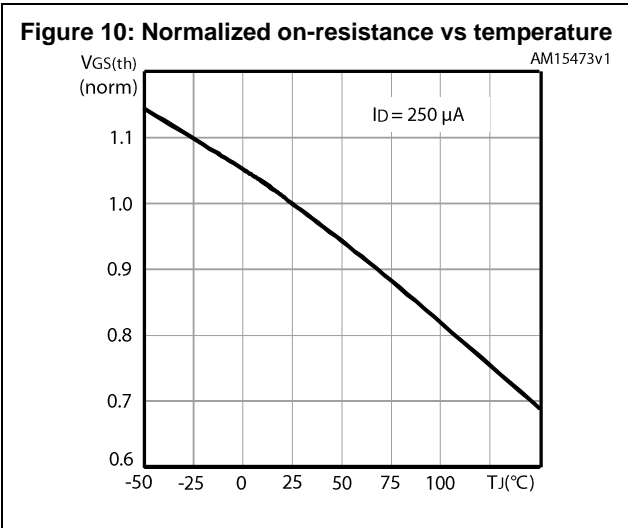
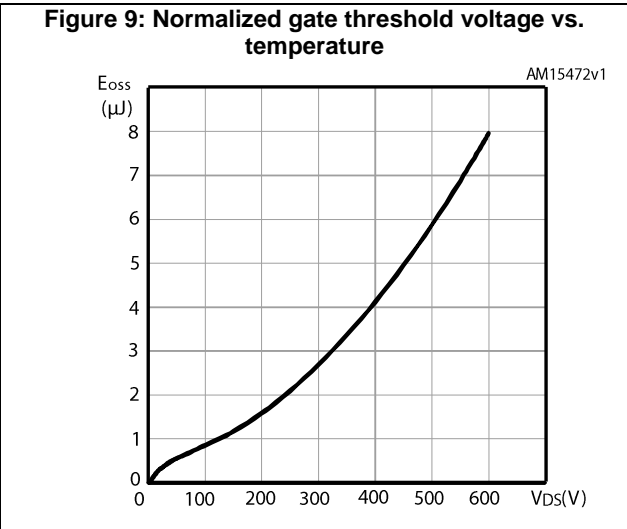
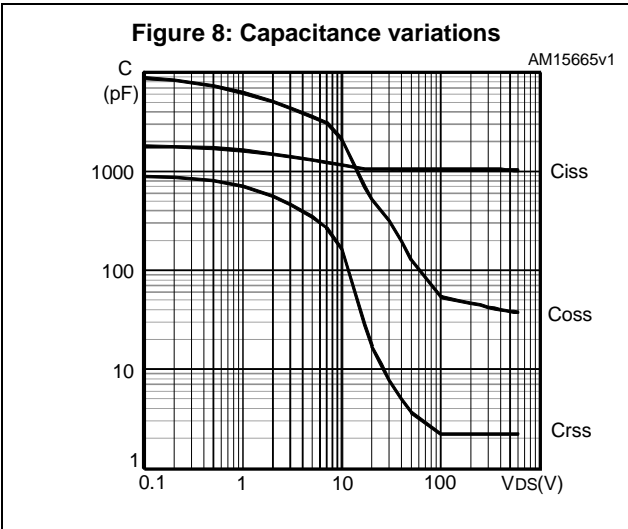
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}^{(1)}$	Source-drain current		-		18	A
$I_{SDM}^{(1)(2)}$	Source-drain current (pulsed)		-		72	A
$V_{SD}^{(3)}$	Forward on voltage	$I_{SD} = 18 \text{ A}$ , $V_{GS} = 0 \text{ V}$	-		1.6	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 18 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$ , $V_{DD} = 60 \text{ V}$ ( see <a href="#">Figure 16: "Test circuit for inductive load switching and diode recovery times"</a> )	-	332		ns
$Q_{rr}$	Reverse recovery charge		-	4		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	24		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 18 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$ , $V_{DD} = 60 \text{ V}$ , $T_j = 150 \text{ }^\circ\text{C}$ , (see <a href="#">Figure 16: "Test circuit for inductive load switching and diode recovery times"</a> )	-	450		ns
$Q_{rr}$	Reverse recovery charge		-	5.5		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	25		A

**Notes:**

- (1)The value is rated according to  $R_{thj-case}$  and limited by package.  
(2)Pulse width limited by safe operating area.  
(3)Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

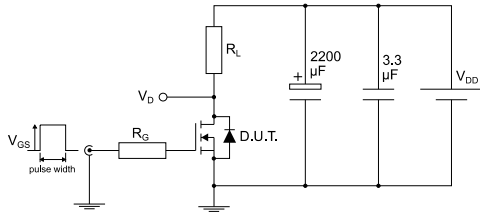
## 2.1 Electrical characteristics (curves)





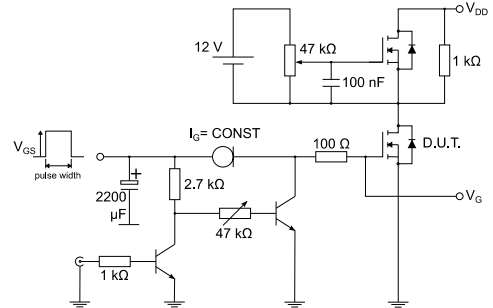
### 3 Test circuit

**Figure 14: Test circuit for resistive load switching times**



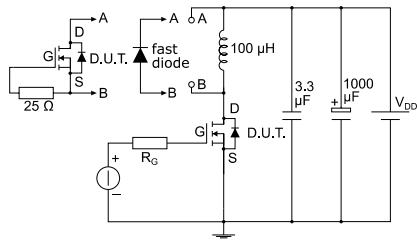
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**Figure 15: Test circuit for gate charge behavior**



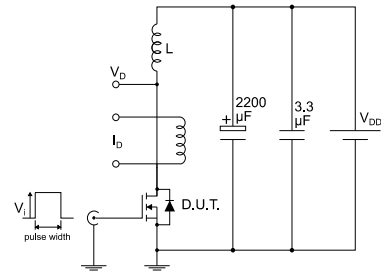
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**Figure 16: Test circuit for inductive load switching and diode recovery times**



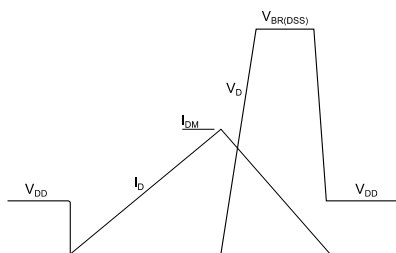
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**Figure 17: Unclamped inductive load test circuit**



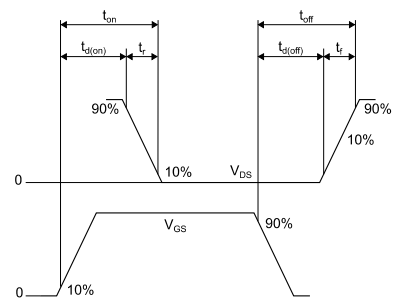
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**Figure 18: Unclamped inductive waveform**



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**Figure 19: Switching time waveform**



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## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 TO-220FP package information

Figure 20: TO-220FP ultra narrow leads package outline

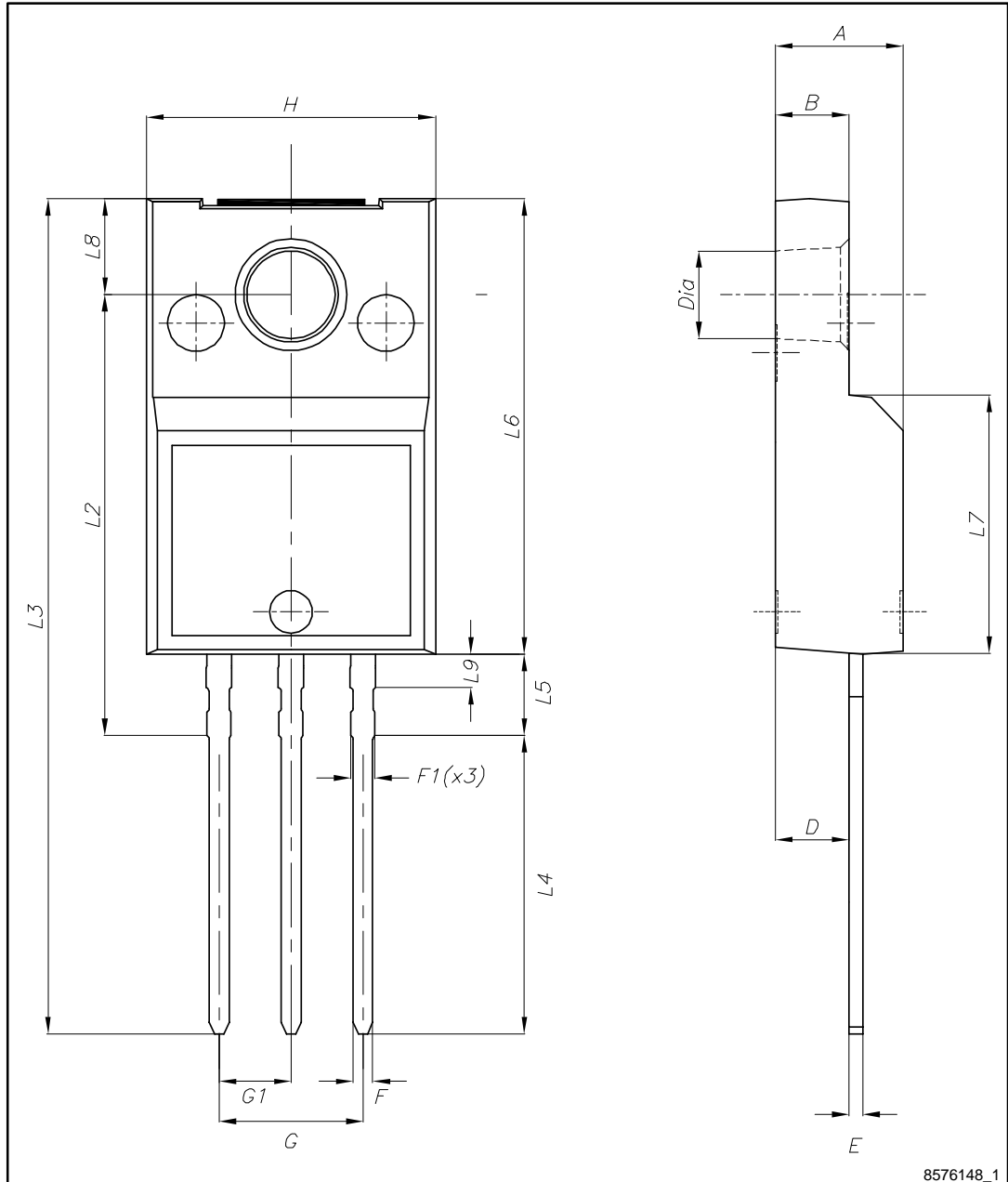


Table 9: TO-220FP ultra narrow leads mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
B	2.50		2.70
D	2.50		2.75
E	0.45		0.60
F	0.65		0.75
F1	-		0.90
G	4.95		5.20
G1	2.40	2.54	2.70
H	10.00		10.40
L2	15.10		15.90
L3	28.50		30.50
L4	10.20		11.00
L5	2.50		3.10
L6	15.60		16.40
L7	9.00		9.30
L8	3.20		3.60
L9	-		1.30
Dia.	3.00		3.20

## 5 Revision history

Table 10: Document revision history

Date	Revision	Changes
12-Mar-2015	1	Initial release
08-Sept-2015	2	Datasheet status promoted from preliminary to production data

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